



General Description

The WST4041 is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WST4041 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

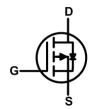
BVDSS	RDSON	ID
-40V	30mΩ	-6A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter.
- Networking DC-DC Power System
- Load Switch

SOT-23-3L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-6.0	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-4.5	А
I _{DM}	Pulsed Drain Current ²	-24	А
EAS	Single Pulse Avalanche Energy ³	12	mJ
I _{AS}	Avalanche Current	-7	Α
P _D @T _C =25°C	Total Power Dissipation⁴	1.4	W
T _{STG}	T _{STG} Storage Temperature Range -55 to 150		$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹		125	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		36	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA		-0.03		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A		30	40	0
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-1A		40	58	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . I _D =-250uA	-0.8	-1.2	-2.2	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , I _D 2500A		4.56		mV/℃
	Drain Source Leakage Current	V _{DS} =-28V , V _{GS} =0V , T _J =25℃			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-28V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V_{DS} =-5V , I_D =-3A		15		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.8		Ω
Q_{g}	Total Gate Charge (-4.5V)	V _{DS} =-18V , V _{GS} =-10V , I _D =-4A		9.5		
Q_{gs}	Gate-Source Charge			1.7		nC
Q_{gd}	Gate-Drain Charge			2.0		
T _{d(on)}	Turn-On Delay Time			8		
T _r	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		10		20
T _{d(off)}	Turn-Off Delay Time	R_G =6 Ω , I_D =-1A , R_L =15 Ω		18		ns
T _f	Fall Time			8		
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		420		
Coss	Output Capacitance			77		pF
C _{rss}	Reverse Transfer Capacitance			55		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-8A	10			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-1.0	Α
I _{SM}	Pulsed Source Current ^{2,6}				-16	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2% 3.The EAS data shows Max. rating . The test condition is V_{DD}=-25V,V_{GS}=-10V,L=0.1mH,I_{AS}=-8A
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.





Typical Characteristics

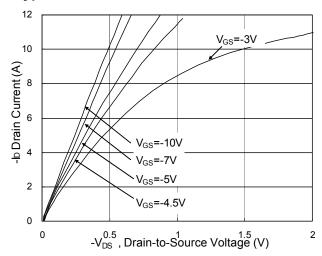


Fig.1 Typical Output Characteristics

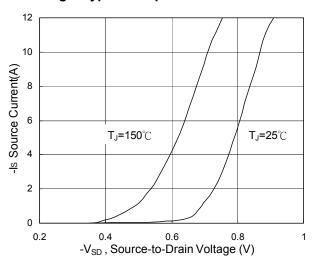


Fig.3 Forward Characteristics of Reverse

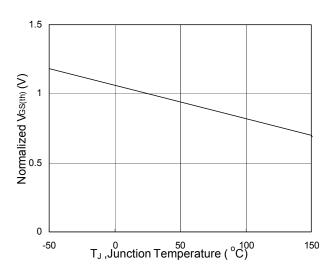


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

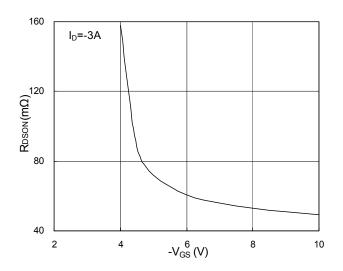


Fig.2 On-Resistance v.s Gate-Source

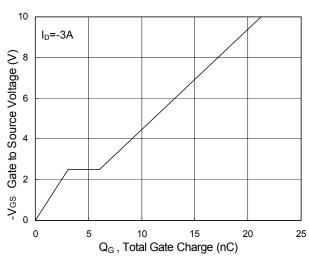


Fig.4 Gate-Charge Characteristics

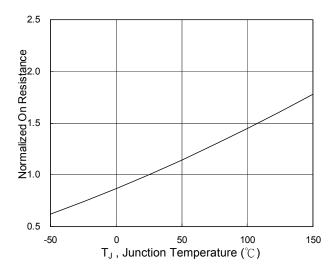
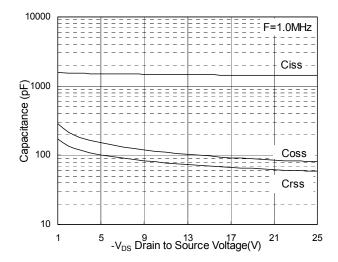


Fig.6 Normalized R_{DSON} v.s T_J







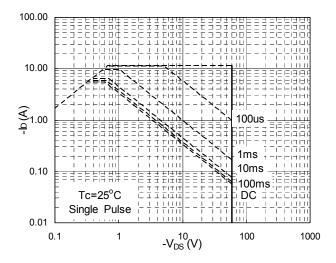


Fig.7 Capacitance

Fig.8 Safe Operating Area

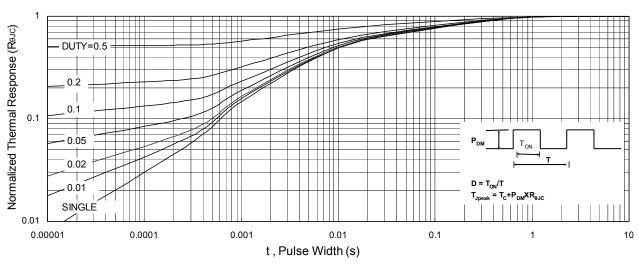


Fig.9 Normalized Maximum Transient Thermal Impedance

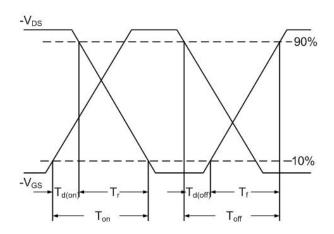


Fig.10 Switching Time Waveform

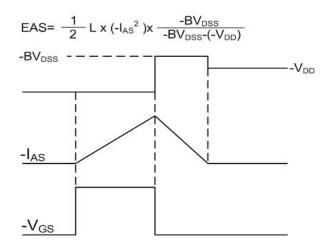


Fig.11 Unclamped Inductive Waveform



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